

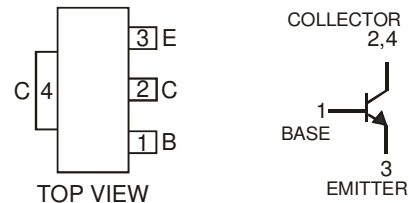
### Features

- Epitaxial Planar Die Construction
- Complementary PNP Type Available (DCP53)
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**



### Mechanical Data

- Case: SOT-223
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish - Matte Tin annealed over Copper leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Marking & Type Code Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.115 grams (approximate)



Schematic and Pin Configuration

### Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Units
Collector-Base Voltage	V <sub>CB0</sub>	100	V
Collector-Emitter Voltage	V <sub>CEO</sub>	80	V
Emitter-Base Voltage	V <sub>EBO</sub>	5	V
Collector Current	I <sub>C</sub>	1	A

### Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation @ T <sub>A</sub> = 25°C (Note 3)	P <sub>d</sub>	1	W
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	-55 to 150	°C
Thermal Resistance, Junction to Ambient Air @T <sub>A</sub> = 25°C (Note 3)	R <sub>θJA</sub>	125	°C/W

### Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 4)</b>						
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	100	—	—	V	I <sub>C</sub> = 100μA, I <sub>E</sub> = 0
Collector-Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	80	—	—	V	I <sub>C</sub> = 10mA, I <sub>B</sub> = 0
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	5.0	—	—	V	I <sub>E</sub> = 10μA, I <sub>C</sub> = 0
Collector-Base Cutoff Current	I <sub>CB0</sub>	—	—	0.1 20	μA	V <sub>CB</sub> = 30V, I <sub>E</sub> = 0 V <sub>CB</sub> = 30V, I <sub>E</sub> = 0, T <sub>A</sub> = 150°C
Emitter-Base Cutoff Current	I <sub>EBO</sub>	—	—	10	μA	V <sub>EB</sub> = 5.0V, I <sub>C</sub> = 0
<b>ON CHARACTERISTICS (Note 4)</b>						
DC Current Gain	h <sub>FE</sub>	25	—	—	—	I <sub>C</sub> = 5.0mA, V <sub>CE</sub> = 2.0V I <sub>C</sub> = 150mA, V <sub>CE</sub> = 2.0V I <sub>C</sub> = 500mA, V <sub>CE</sub> = 2.0V
		40	—	250		
		25	—	—		
		100	160	250		
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	—	—	0.5	V	I <sub>C</sub> = 500mA, I <sub>B</sub> = 50mA
Base-Emitter Turn-On Voltage	V <sub>BE(ON)</sub>	—	—	1.0	V	I <sub>C</sub> = 500mA, V <sub>CE</sub> = 2.0V
<b>SMALL SIGNAL CHARACTERISTICS</b>						
Current-Gain-Bandwidth Product	f <sub>T</sub>	—	200	—	MHz	I <sub>C</sub> = 50mA, V <sub>CE</sub> = 5.0V, f = 100MHz

- Notes:
1. No purposefully added lead.
  2. Diodes Inc.'s "Green" Policy can be found on our website at [http://www.diodes.com/products/lead\\_free/index.php](http://www.diodes.com/products/lead_free/index.php).
  3. Device mounted on FR-4 PCB; pad layout as shown on page 4 or in Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
  4. Pulse Test: Pulse width = ≤300μs, Duty Cycle ≤ 2%.

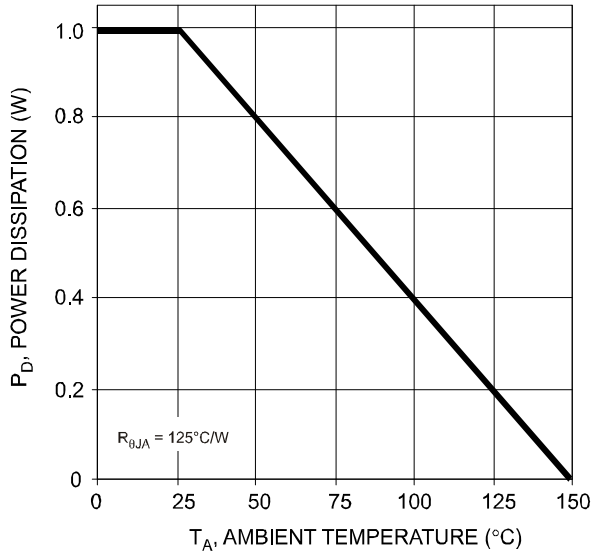


Fig. 1 Power Dissipation vs. Ambient Temperature

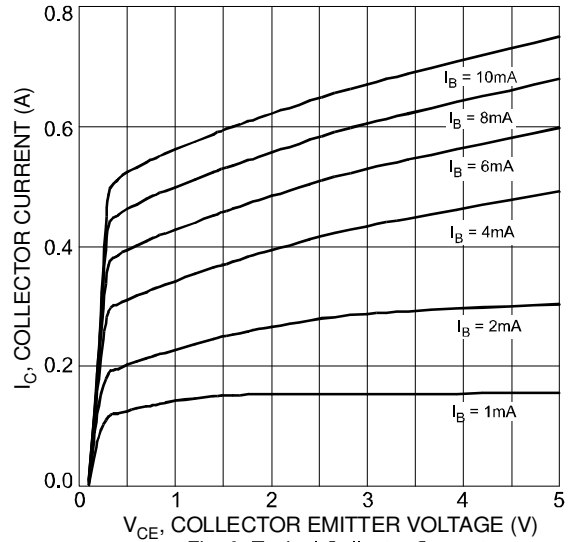


Fig. 2 Typical Collector Current vs. Collector Emitter Voltage

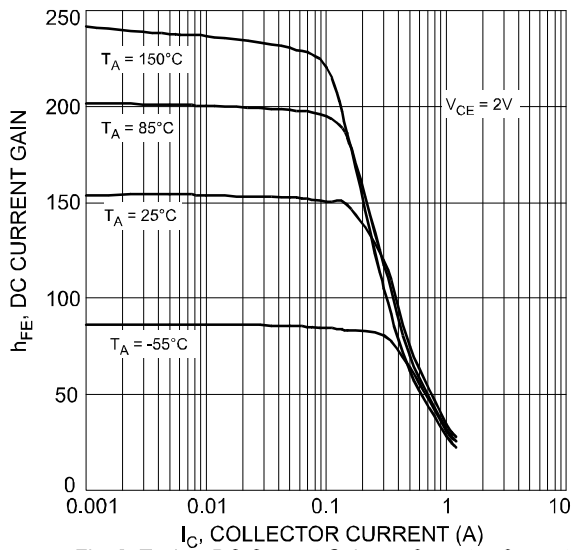


Fig. 3 Typical DC Current Gain vs. Collector Current

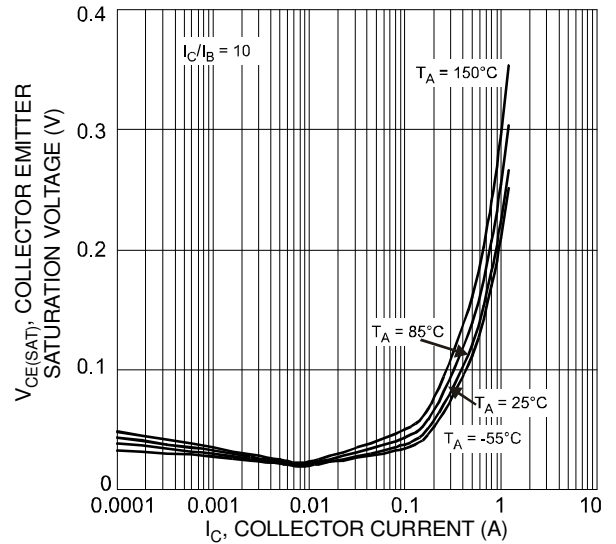


Fig. 4 Typical Collector Emitter Saturation Voltage vs. Collector Current

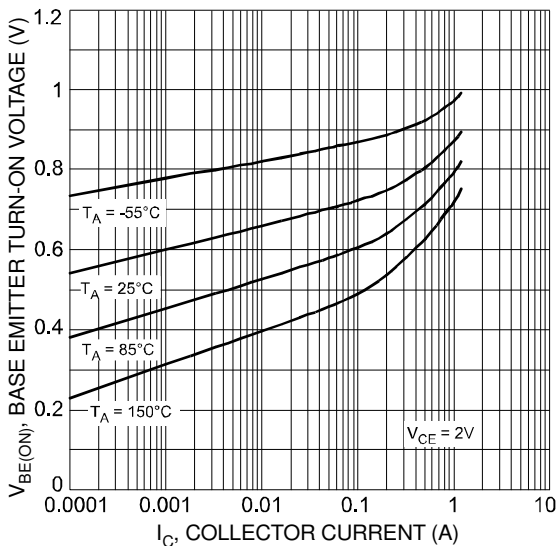


Fig. 5 Typical Base Emitter Turn-On Voltage vs. Collector Current

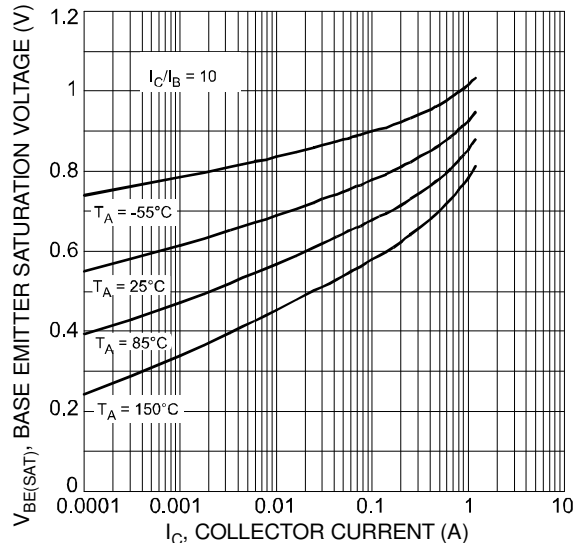


Fig. 6 Typical Base Emitter Saturation Voltage vs. Collector Current

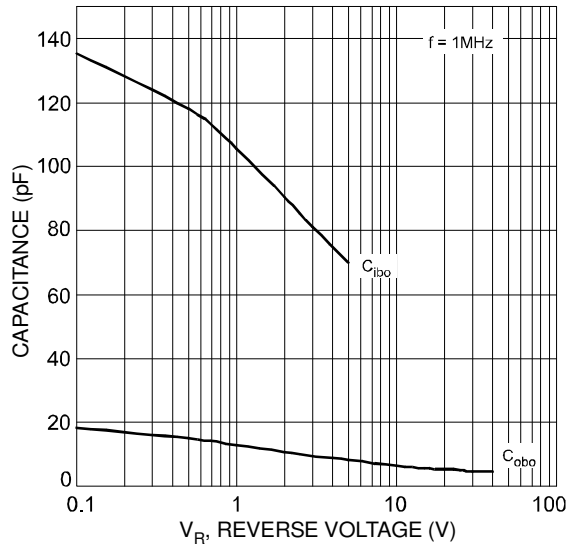


Fig. 7 Typical Capacitance Characteristics

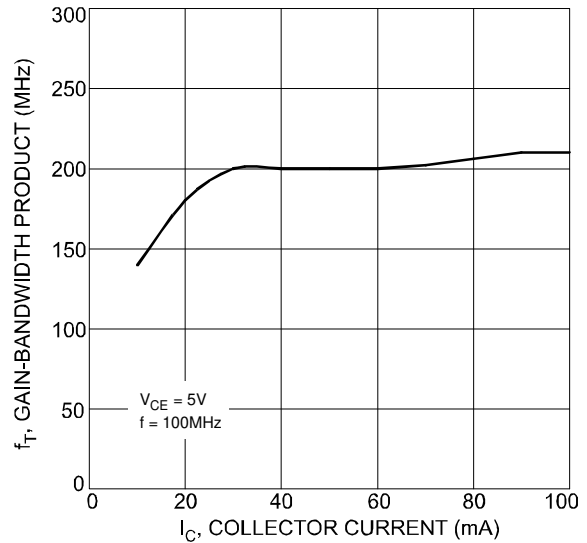


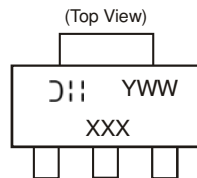
Fig. 8 Typical Gain-Bandwidth Product vs. Collector Current

### Ordering Information (Note 5)

Device	Packaging	Shipping
DCP56-13	SOT-223	2500/Tape & Reel
DCP56-16-13	SOT-223	2500/Tape & Reel

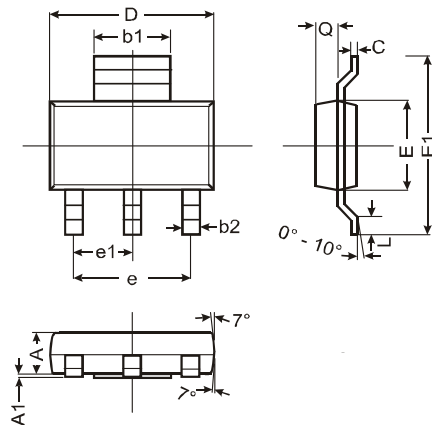
Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

### Marking Information



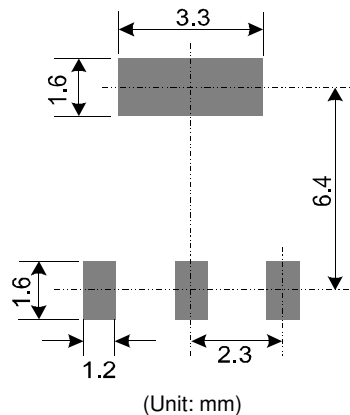
XXX = Product Type Marking Code ex. N18 = DCP56  
N18-16 = DCP56-16  
D = Manufacturer's Marking Code  
YWW = Date Code Marking  
Y = Last Digit of Year ex: 7 = 2007  
WW = Week Code 01-52

### Package Outline Dimensions



SOT-223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b1	2.90	3.10	3.00
b2	0.60	0.80	0.70
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	—	—	4.60
e1	—	—	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89

All Dimensions in mm

**Suggested Pad Layout: (Based on IPC-SM-782)****IMPORTANT NOTICE**

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